P.3

Amended claims

- Claim 1. A hot melt adhesive composition comprising, by weight of the hot melt adhesive composition,
- a) about 5 weight percent to about 60 weight percent of an ethylene vinyl acetate copolymer having a vinyl acetate content of about 30 weight percent to 50 weight percent and a melt index of about 700 to 4,000 dg/min;
 - b) about 5 weight percent to about 60 weight percent of a tackifier; and
- c) about 15 weight percent to about 55 weight percent of a wax with a melting point of about 125°F to 180°F;

wherein the hot melt composition can be applied at a temperature of 200°F to 300°F.

- Claim 6. An adhesive according to Claim 1 wherein the wax is paraffin wax or synthetic wax.
- Claim 8. A hot melt adhesive composition comprising, by weight of the hot melt adhesive composition,
- a) about 35 weight percent of an ethylene vinyl acetate copolymer with about 40 weight percent vinyl acetate and having a melt index of at about 1,000;
- b) about 30 weight percent of a tackifier selected from the group consisting of terpene, terpene phenolic, modified terpenes, and combinations thereof;
- c) about 5 weight percent of at least one additional tackifier selected from the group consisting of pentaerythritol, hydrogenated glycerol, and combinations thereof;
- d) about 30 weight percent of a wax with a melting point of about 150°F; wherein the hot melt composition can be applied at a temperature of 200°F to 300°F.
- Claim 10. An adhesive according to Claim 3 which comprises a terpene phenolic tackifier.

P.4

- An adhesive according to Claim 1 which comprises about 35 weight Claim 11. percent to about 45 weight percent of an ethylene vinyl acetate copolymer.
- A method of bonding substrates together, said method comprising Claim 12. applying, at an application temperature of 200°F to 300°F, the hot melt adhesive composition of claim 1 to a first substrate, bringing a second substrate in contact with the composition applied to the first substrate, whereby the first substrate becomes bonded to the second substrate.